SMART-ReAD: Al-driven detector readout for physics experiments

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- Goal: Development of an electronics platform to implement an embedded processing of detector signals by means of AI techniques and its deployment in experiments infrastructures
- **Detector types:** segmented detectors where **event signals are distributed over several units**
- Advantages: simplify the event processing still keeping performances, reduction the computational resources and power, compared to event processing by external computational units

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Development approaches

 Processing the detector signals by means of AI algorithms, in particular Machine Learning (ML):



 Moving the processing of the event for feature extraction (position, energy, timing) closer to the detector and FE electronics.
Employment of In-Memory Computing approach:







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Real-time event reconstruction in FPGA



- Implementation of a **Artificial Neural Network in FPGA** for real-time reconstruction of gamma-ray events (energy, position) in thick scintillators
- 2.9mm spatial resolution, 5us/event processing time



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ANNA (Analog Neural Network ASIC)





S. Di Giacomo, et al., in IEEE TRPMS, vol. 9, no. 5, pp. 542-552, 2025.

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Hadron Physics in Horizon Europe, Nantes, 01/07/2025

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LGAD Resistive Silicon Sensors (RDS)



- the resistive implant collecting the charge acts as a signal divider;
- information about position, energy, and timing is encoded in how the signal is split among nearby readout electrodes;
- RSDs reduce the number of readout channels of a factor of ~100 compared to standard sensors;
- machine-learning techniques provide better results than analytical algorithms in reconstructing the events.



Goals:

- Develop a proof-of-concept low-power ML-RSD tracker to be tested in beam test facilities (spatial res. ≠ pixel dimensions!). Low-power 4D detector: an ECFA milestone.
- Prototype of a new telescope detector to be installed in beam test facilities

F. Siviero, et al., JINST, 19 C01028.



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Scintillator detectors for gamma-ray spectroscopy, imaging, calorimetry ⁶



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Project plan

Project activities

- Development of an electronics platform for AI-processing of detector signals, based on FPGAs and ASICs, available both as stand-alone units and integrated in the detector module
- Compatible with different detector types: LGAD-RDS, scintillators, Ge, CdTe/CZT,..
- Event features extraction (position, energy, timing), particle identification by PSA
- Integration and validation in experiment facilities (see next slide)

Topics of interest in the call

- Short-term R&D, AI technologies, Applications and links with industry.
- Aim to contribute to **improve the efficiency of the infrastructures in complex detection apparatus of hadron physics experiments** (Work programme: .. *improve the services the infrastructures provide and to further develop their on-line services).*
- Potential impact also in **applied physics applications**, as nuclear medical imaging (e.g. PET, Range Verification in Hadron Therapy), as well as towards **innovative industrial instruments**.



RSD detectors

Beam test facilities

- CERN SPS, Geneve
 - 120 GeV/c pions & protons beams
 - Particle tracker available upon request
- LNF, Beam Test Facility, Frascati
 - e+ 50 550 MeV
 - e- 50 750 MeV
- MAMI, Mainz
 - e- 0.2 1.6 GeV

Beam test facilities

Scintillator detectors

- IFIN-HH, Bucarest
 - >10 MeV protons
- LNL, Legnaro
 - 28 MeV protons
- IFJ-PAN, Krakow
 - 70 230 MeV protons

Irradiation facilities

- Neutron irradiation: Liubjiana TRIGA reactor,
- Proton irradiation: IRRAD, CERN
- Low energy hadron: KIT, Karlsruhe



Participating institutions

- Politecnico di Milano, Dipartimento di Elettronica, Informazione e Bioingegneria
- Università degli Studi di Milano, Dipartimento di Fisica
- INFN, Sezione di Milano / INFN Sezione di Torino
- UPO, Università del Piemonte Orientale

Estimated budget request

- 4 FTEs for designers (140k), 1 FTE for detector development (35k)
- ASIC runs (80k), sensors production (60k)
- FPGAs, PCBs, el. components (30k),
- beam tests and travels (40k)
- overheads (60k)
- Tot. 445k

